

SCHOTTKY BARRIER RECTIFIERS 20A

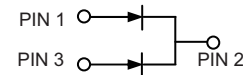
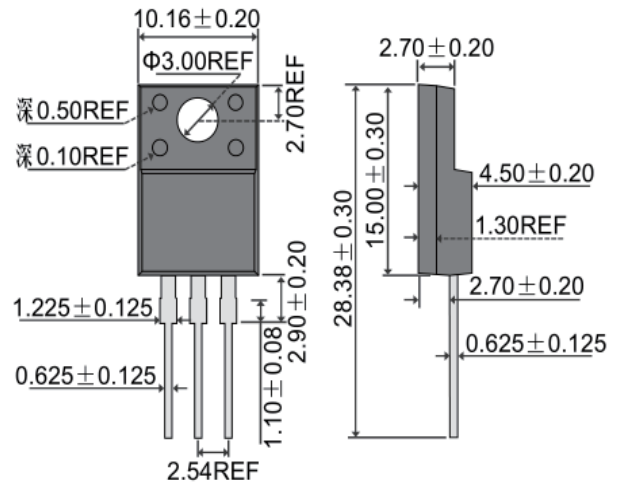
Features

- Power Schottky Barrier Chip
- Guard Ring for Transient Protection
- Low Forward Voltage Drop
- Low Power Loss, High Efficiency
- High Surge Current Capability
- Epoxy Meets UL 94V-0 Classification
- Ideally Suited for Use in High Frequency SMPS, Inverters and As Free Wheeling Diodes

Mechanical Data

- Case: ITO-220, Full Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: See Diagram
- Weight: 1.9 grams (approx.)
- Mounting Position: Any
- Mounting Torque: 0.6 N.m Max.
- Lead Free: For RoHS / Lead Free Version

ITO-220AB



Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	SRF 2020CT	SRF 2030CT	SRF 2040CT	SRF 2045CT	SRF 2050CT	SRF 2060CT	SRF 2080CT	SRF 20100CT	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	20	30	40	45	50	60	80	100	V
Working Peak Reverse Voltage	V _{RWM}									V
DC Blocking Voltage	V _R									V
RMS Reverse Voltage	V _{R(RMS)}	14	21	28	32	35	42	56	70	V
Average Rectified Output Current @T _C = 100°C	I _O	20 10								A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	150								A
Forward Voltage @I _F = 10A, T _J = 25°C per diode	V _{FM}	0.55 0.50			0.75 0.65		0.85 0.75			V
Peak Reverse Current At Rated DC Blocking Voltage	I _{RM}	0.5 20								mA
Typical Junction Capacitance (Note 1)	C _J	650				350				pF
Thermal Resistance Junction to Ambient per diode	R _{θJA}	62								°C/W
Thermal Resistance Junction to Case per diode	R _{θJC}	4.0								
RMS Isolation Voltage, t = 1 min	V _{ISO}	1500								V
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150								°C

Note: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.



RATINGS AND CHARACTERISTIC CURVES

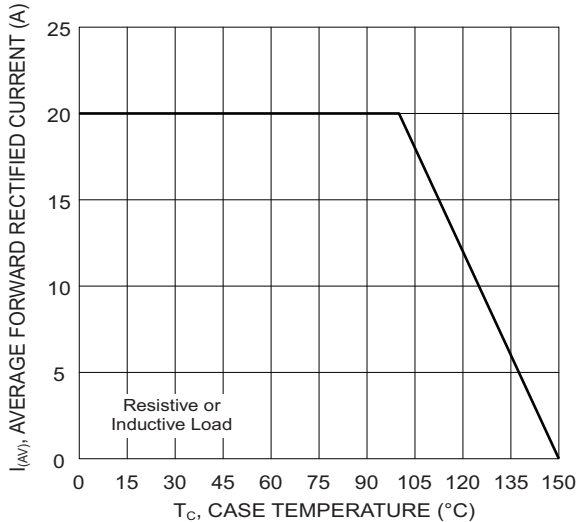


Fig. 1 Forward Current Derating Curve

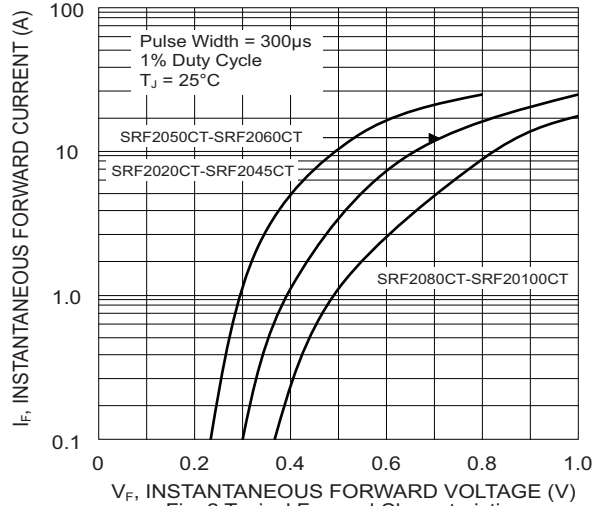


Fig. 2 Typical Forward Characteristics

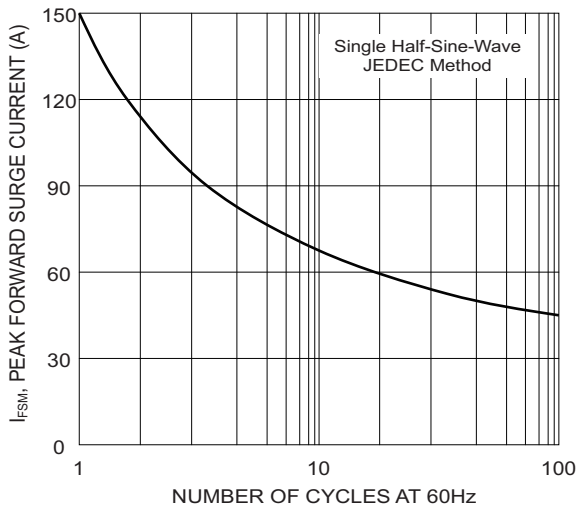


Fig. 3 Forward Surge Current Derating Curve

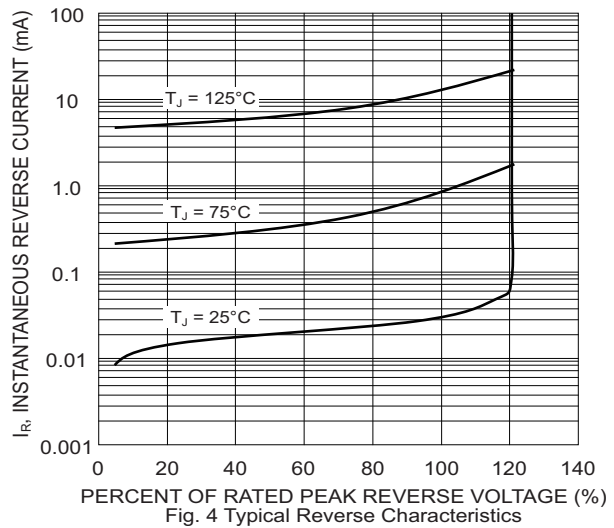


Fig. 4 Typical Reverse Characteristics

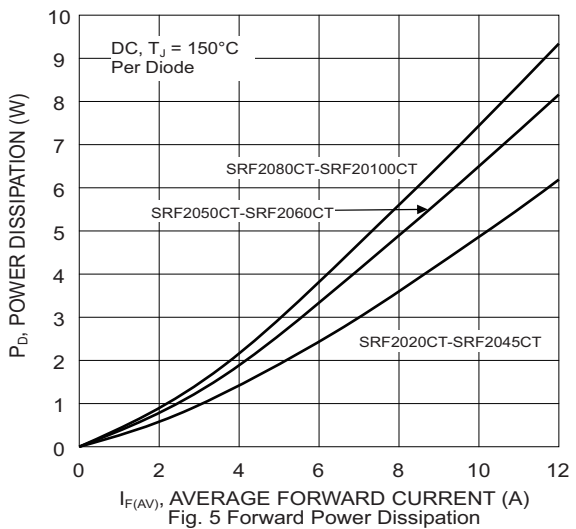


Fig. 5 Forward Power Dissipation

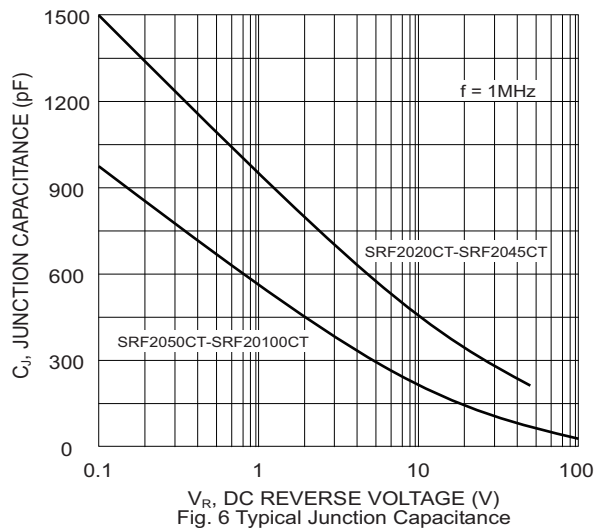


Fig. 6 Typical Junction Capacitance



PACKAGING INFORMATION

BULK

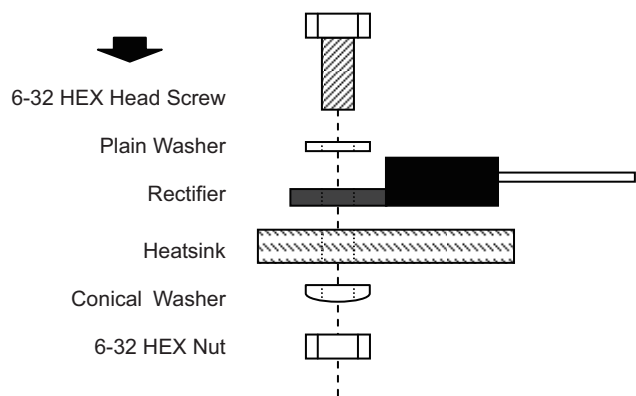
Tube Size L x W x H (mm)	Quantity (PCS)	Inner Box Size L x W x H (mm)	Quantity (PCS)	Carton Size L x W x H (mm)	Quantity (PCS)	Approx. Gross Weight (KG)
525 x 31 x 6	50	558 x 150 x 40	1,000	570 x 235 x 170	5,000	11.85

RECOMMENDED SCREW MOUNTING ARRANGEMENT

The full molded plastic package affords a major reduction of hardware as compared to a standard TO-220 package. However, precautions should be made in mounting procedure.

A conical washer should be used to apply proper force to the device. Screw should not be tightened with any type of air-forced torque or equipment that may cause crack on device package.

A layer of thermal grease or thermal pad in the interface will be considerably helpful for heat dissipation.





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